

Features

- Proprietary New Trench Technolog
- Fast Recovery Body Diode
- Low Gate Charge Minimize Switching Loss

BVDSS		120	V
ID@VGS= 10V , TC=25°C		110	A
RDSON(MAX)	VGS = 10 V , ID = 45 A	7.2	mΩ

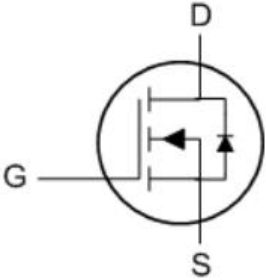
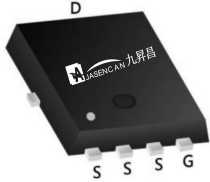
Application

- DC/DC Converter
- Ideal for high-frequency switching and synchronous rectification

Description

The JSA064N12A is the high cell density trenched N-Ch MOSFETs, which provide excellent RDSON and gate charge for applications.

The EHBA064N12A meet the RoHS and Green Product requirement, 100% EAS guaranteed with full function reliability approved.

Equivalent Circuit	Outline
	<p>PRPAK5×6</p> 

Package Marking and Ordering Information

Device Marking	Date Code	Device Package	Quantity
A064N12A	YWWXXX	PRPAK5×6	5000 pcs

Thermal Characteristic

Symbol	Parameter	Value	Unit
$R_{\theta JA}$	Thermal Resistance Junction-Ambient ¹	50	°C/W
$R_{\theta JC}$	Thermal Resistance Junction-Case ¹	0.78	°C/W

Absolute Maximum Ratings

Symbol	Parameter	Rating	Unit
V_{DS}	Drain-Source Voltage	120	V
V_{GS}	Gate-Source Voltage	±20	V
I_D	Continuous Drain Current, $V_{GS} @ 10V$ ¹ ($T_C=25^\circ C$)	110	A
	Continuous Drain Current, $V_{GS} @ 10V$ ¹ ($T_C=100^\circ C$)	70	
I_{DM}	Pulsed Drain Current ²	440	A
P_D	Total Power Dissipation ⁴ ($T_C=25^\circ C$)	160	W
	Total Power Dissipation ⁴ ($T_C=100^\circ C$)	64	
E_{AS}	Single Pulse Avalanche Energy ³	223	mJ
I_{AS}	Avalanche Current	66.8	A
T_J, T_{STG}	Operating Junction and Storage Temperature Range	-55 To 150	°C

Electrical Characteristics ($T_J=25^\circ C$ unless otherwise noted)

Staic Characteristics						
Symbol	Parameter	Conditions	Min	Typ	Max	Unit
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{GS} = 0V, I_D = 250 \mu A$	120			V
$R_{DS(ON)}$	Drain-Source On-State Resistance ²	$V_{GS} = 10V, I_D = 45A$		6.4	7.2	mΩ
$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS} = V_{DS}, I_D = 250 \mu A$	2.5		4.5	V
I_{DSS}	Drain-Source Leakage Current ($T_J=25^\circ C$)	$V_{DS} = 120V, V_{GS} = 0V$			1	μA
	Drain-Source Leakage Current ($T_J=125^\circ C$)	$V_{DS} = 96V, V_{GS} = 0V$			100	
I_{GSS}	Gate-Body Leakage Current	$V_{GS} = \pm 20V, V_{DS} = 0V$			±100	nA

Dynamic Characteristics						
Symbol	Parameter	Conditions	Min	Typ	Max	Unit
C_{iss}	Input Capacitance	$V_{DS} = 60\text{ V}$		2950		pF
C_{oss}	Output Capacitance	$V_{GS} = 0\text{ V}$		845		pF
C_{rss}	Reverse Transfer Capacitance	$f=1.0\text{ MHz}$		9.9		pF
Switching Times						
Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$t_{d(on)}$	Turn-On Delay Time	$V_{DD} = 60\text{ V}$		23		nS
t_r	Turn-On Rise Time	$V_{GS} = 10\text{ V}$		6.7		nS
$t_{d(off)}$	Turn-Off Delay Time	$R_G = 3.3\ \Omega$		28		nS
t_f	Turn-Off Fall Time	$I_D = 55\text{ A}$		7.1		nS
Q_g	Total Gate Charge (10 V)	$V_{DS} = 60\text{ V}$		36		nC
Q_{gs}	Gate-Source Charge	$V_{GS} = 10\text{ V}$		15		nC
Q_{gd}	Gate-Drain Charge	$I_D = 55\text{ A}$		6		nC

Source-Drain Diode Characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
I_S	Continuous Source Current ^{1,5}	$V_G=V_D=0\text{ V}$, Force Current			110	A
I_{SM}	Pulsed Source Current ^{2,5}				440	A
V_{SD}	Diode Forward Voltage ²	$I_S = 90\text{ A}$, $V_{GS}=0\text{ V}$, $T_J=25^\circ\text{C}$			1.2	V
t_{rr}	Reverse Recovery Time	$I_F = 35\text{ A}$, $dI/dt = 100\text{ A}/\mu\text{s}$,		78		nS
Q_{rr}	Reverse Recovery Charge	$T_J=25^\circ\text{C}$		33		nC

Notes:

1. The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.
2. The data tested by pulsed : Pulse Width $\leq 300\mu\text{s}$, Duty Cycle $\leq 2\%$.
3. The E_{AS} data shows Max. rating . The test condition is $V_{DD} = 50\text{ V}$, $V_{GS} = 10\text{ V}$, $L = 0.1\text{ mH}$, $I_{AS} = 66.8\text{ A}$.
4. The power dissipation is limited by 150°C junction temperature.
5. The data is theoretically the same as I_D and I_{DM} , in real applications , should be limited by total power dissipation.

Typical Characteristics

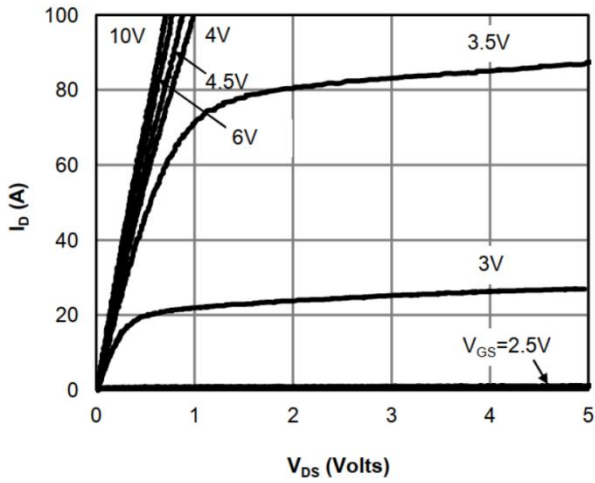


Fig.1 Typical Output Characteristics

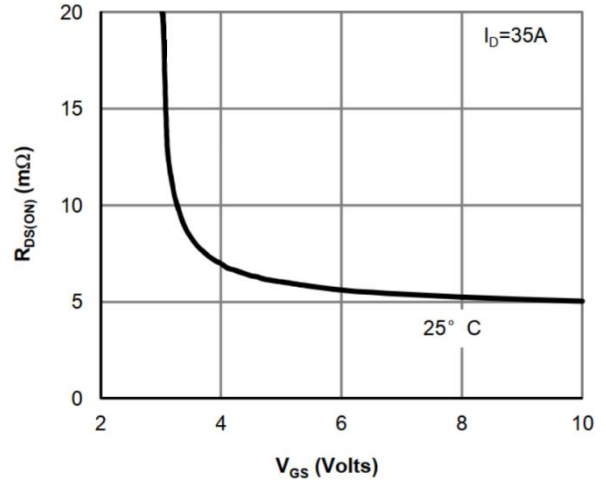


Fig.2 On-Resistance vs. G-S Voltage

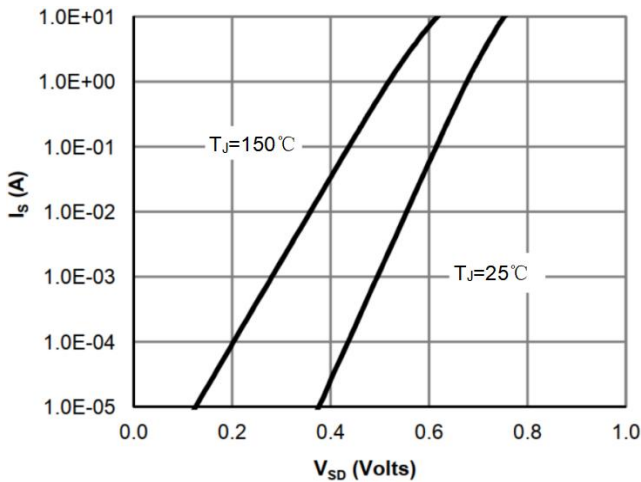


Fig.3 Forward Characteristics Of Reverse

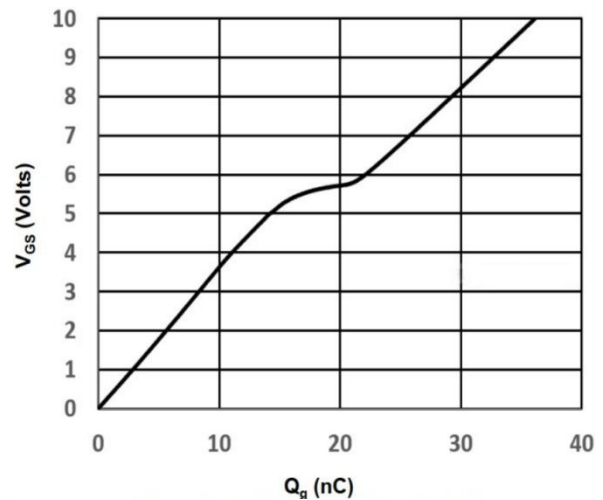


Fig.4 Gate-Charge Characteristics

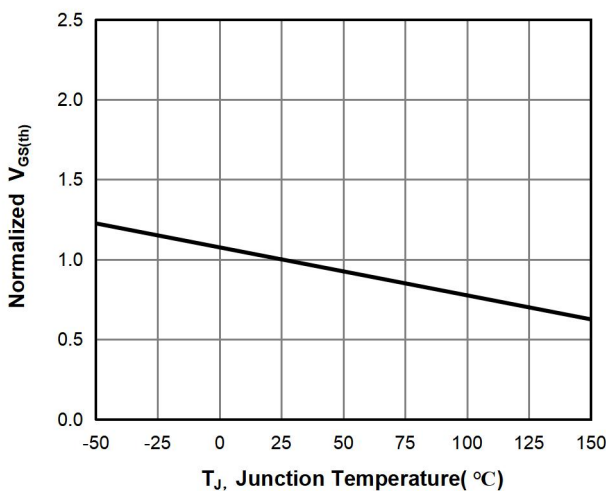


Fig.5 Normalized BV_{DS} vs. T_J

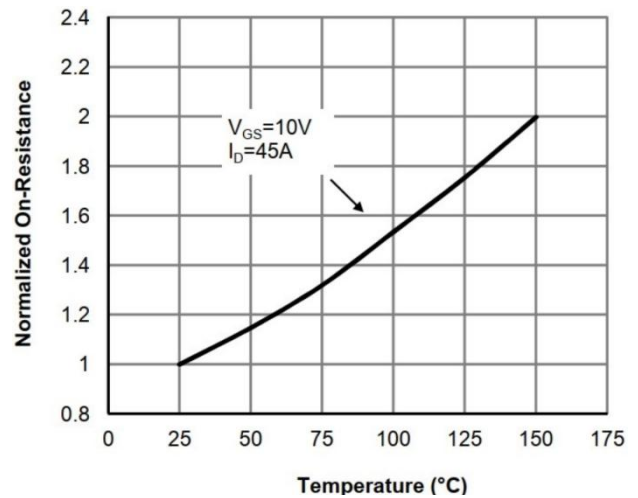


Fig.6 Normalized $R_{DS(on)}$ vs. T_J

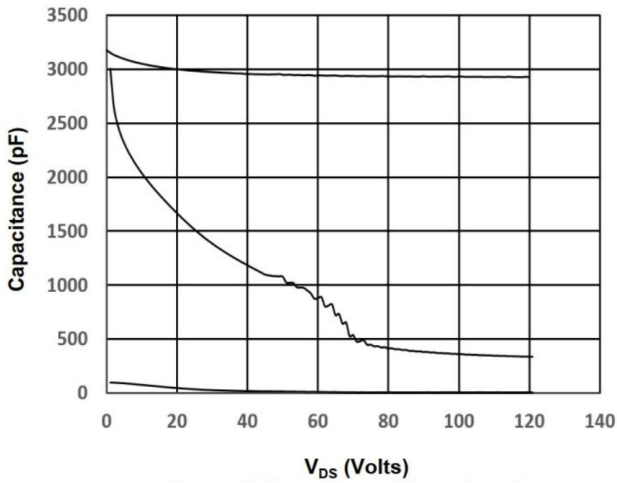


Fig.7 Capacitance

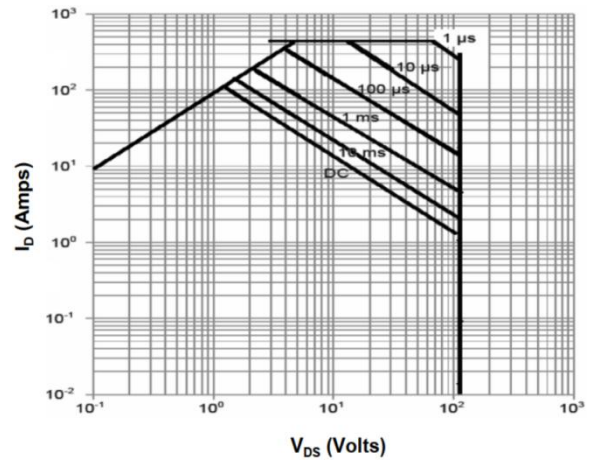


Fig.8 Safe Operating Area

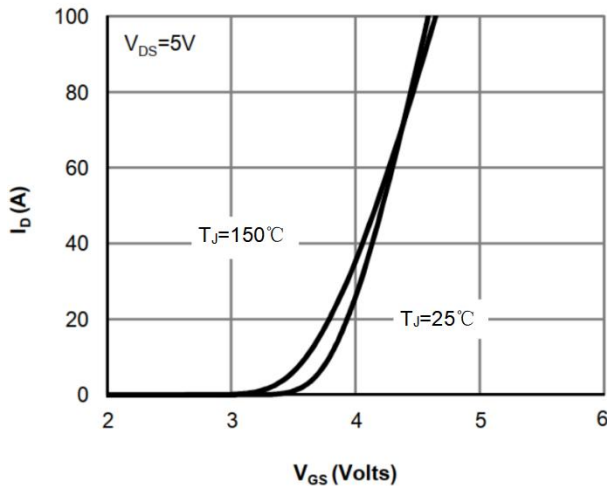


Fig.9 Transfer Characteristics

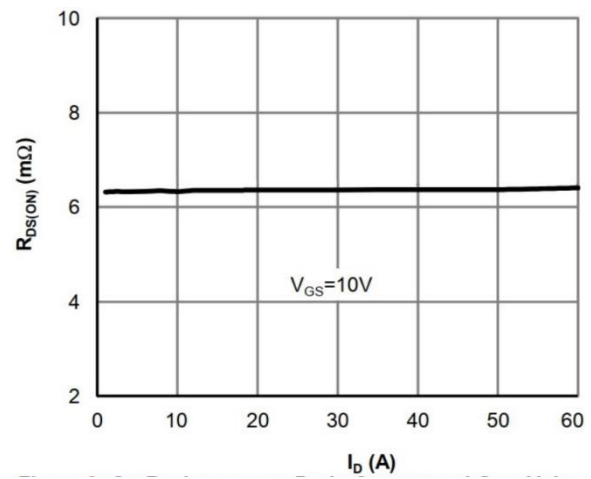


Fig.10 On-Resistance vs. Drain Current

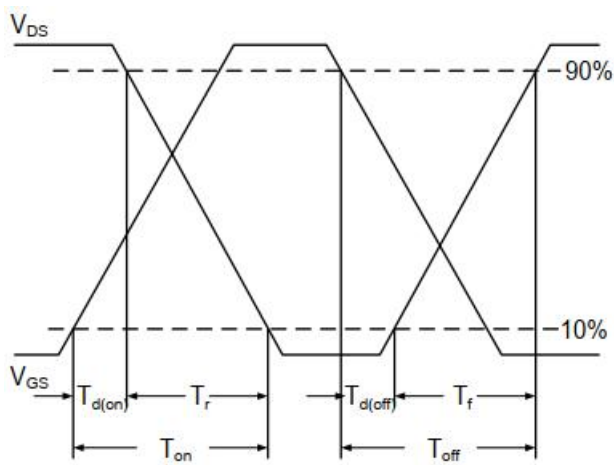


Fig.11 Switching Time Waveform

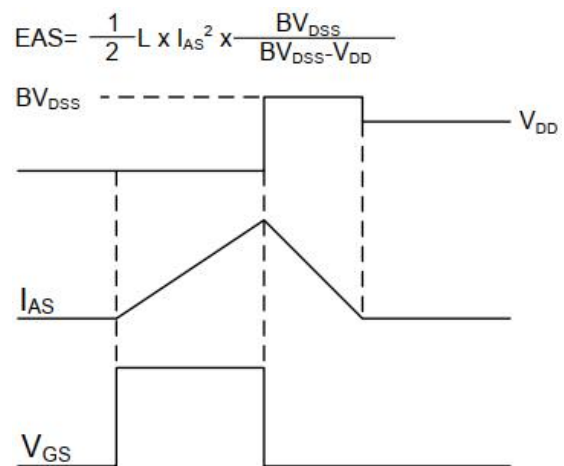
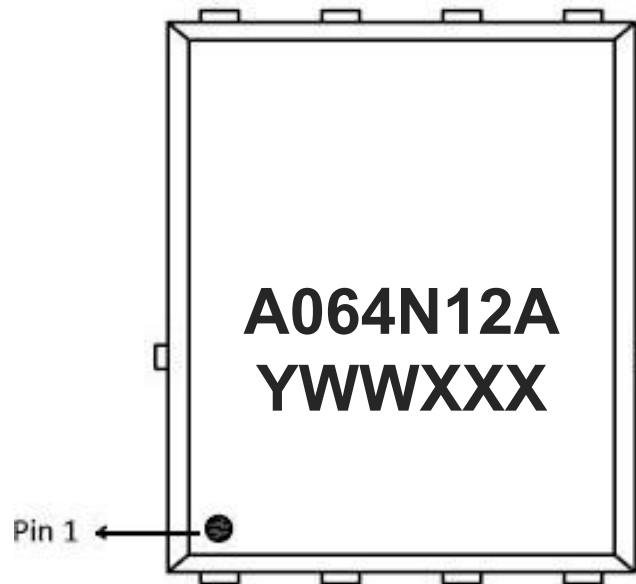


Fig.12 Unclamped Inductive Switching Waveform

Marking Information



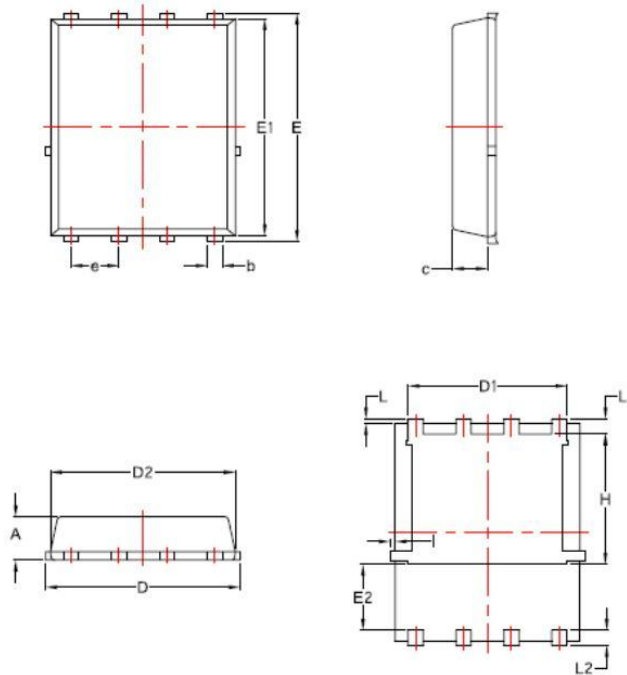
1 st line: HuaYuanWei Logo (left)

2 nd line: Device Package, Part Number, Channel and Version

3 rd line: Date Code [Y WW XX X]

- ① **Y** : Year (2021=M, 2022=N.....)
- ② **WW** : Week (01-53)
- ③ **XX** : Serial Number (01-99, AA-ZZ)
- ④ **X** : Factory Code (A-Z)

PRPAK5×6 Package Outline



SYMBOLS	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	0.90	1.20	0.0354	0.0474
b	0.30	0.51	0.0118	0.0200
c	0.60	1.046	0.0236	0.0412
D1	4.11	4.31	0.1618	0.1697
D2	4.80	5.20	0.1890	0.2047
E	5.90	6.35	0.2323	0.2500
E1	5.65	6.06	0.2224	0.2386
E2	1.10	-	0.0433	-
e	1.27 BSC		0.05 BSC	
L	0.05	0.25	0.0020	0.0098
L1	0.38	0.61	0.0150	0.0240
L2	0.30	0.71	0.0118	0.0280
H	3.30	3.92	0.1300	0.1543
I	-	0.18	-	0.0070